

SN54AHCT540, SN74AHCT540 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCLS268L – DECEMBER 1995 – REVISED JULY 2003

- Inputs Are TTL-Voltage Compatible
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

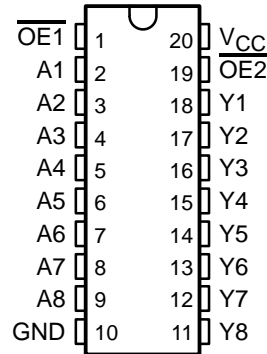
description/ordering information

The 'AHCT540 octal buffers/drivers are ideal for driving bus lines or buffer memory address registers. These devices feature inputs and outputs on opposite sides of the package to facilitate printed circuit board layout.

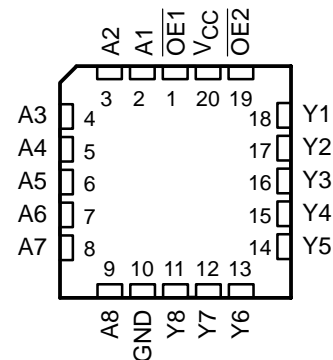
The 3-state control gate is a two-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all corresponding outputs are in the high-impedance state. The outputs provide inverted data when they are not in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

SN54AHCT540 . . . J OR W PACKAGE
SN74AHCT540 . . . DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHCT540 . . . FK PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AHCT540N	SN74AHCT540N
	SOIC – DW	Tube	SN74AHCT540DW	AHCT540
		Tape and reel	SN74AHCT540DWR	
	SOP – NS	Tape and reel	SN74AHCT540NSR	AHCT540
	SSOP – DB	Tape and reel	SN74AHCT540DBR	HB540
	TSSOP – PW	Tube	SN74AHCT540PW	HB540
		Tape and reel	SN74AHCT540PWR	
TVSOP – DGV	Tape and reel	SN74AHCT540DGVR	HB540	
–55°C to 125°C	CDIP – J	Tube	SNJ54AHCT540J	SNJ54AHCT540J
	CFP – W	Tube	SNJ54AHCT540W	SNJ54AHCT540W
	LCCC – FK	Tube	SNJ54AHCT540FK	SNJ54AHCT540FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

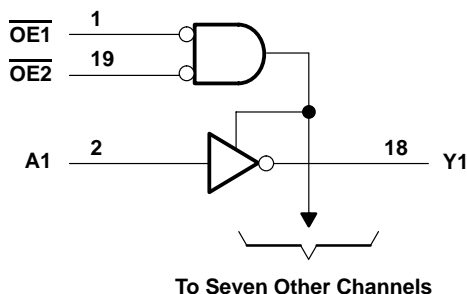
SN54AHCT540, SN74AHCT540 OCTAL BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

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FUNCTION TABLE
(each buffer/driver)

INPUTS			OUTPUT
$\overline{OE1}$	$\overline{OE2}$	A	Y
L	L	L	H
L	L	H	L
H	X	X	Z
X	H	X	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	-0.5 V to 7 V
Input voltage range, V_I (see Note 1)	-0.5 V to 7 V
Output voltage range, V_O (see Note 1)	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	-20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 25 mA
Continuous current through V_{CC} or GND	± 75 mA
Package thermal impedance, θ_{JA} (see Note 2):	
DB package	70°C/W
DGV package	92°C/W
DW package	58°C/W
N package	69°C/W
NS package	60°C/W
PW package	83°C/W
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Note 3)

		SN54AHCT540		SN74AHCT540		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		-8		-8	mA
I _{OL}	Low-level output current		8		8	mA
Δt/Δv	Input transition rise or fall rate		20		20	ns/V
T _A	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AHCT540		SN74AHCT540		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4	V	
	I _{OH} = -8 mA		3.94			3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5 V			0.1	0.1		0.1	V	
	I _{OL} = 8 mA				0.36	0.44	0.44			
I _I	V _I = 5.5 V or GND	0 V to 5.5 V			±0.1	±1*		±1	μA	
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±0.25	±2.5		±2.5	μA	
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			4	40		40	μA	
ΔI _{CC} †	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35	1.5		1.5	mA	
C _i	V _I = V _{CC} or GND	5 V		2	10			10	pF	
C _o	V _O = V _{CC} or GND	5 V		4					pF	

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

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OCTAL BUFFERS/DRIVERS
WITH 3-STATE OUTPUTS

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**switching characteristics over recommended operating free-air temperature range,
 $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54AHCT540		SN74AHCT540		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	$C_L = 15\text{ pF}$	4*	6*	1*	7.5*	1	7.5	ns	
t_{PHL}				4*	6*	1*	7.5*	1	7.5		
t_{PZH}	\overline{OE}	Y	$C_L = 15\text{ pF}$	5.5*	8*	1*	9*	1	9	ns	
t_{PZL}				5.5*	8*	1*	9*	1	9		
t_{PHZ}	\overline{OE}	Y	$C_L = 15\text{ pF}$	5*	8*	1*	9*	1	9	ns	
t_{PLZ}				5*	8*	1*	9*	1	9		
t_{PLH}	A	Y	$C_L = 50\text{ pF}$	6	8.5	1	10	1	10	ns	
t_{PHL}				6	8.5	1	10	1	10		
t_{PZH}	\overline{OE}	Y	$C_L = 50\text{ pF}$	7.5	11	1	12	1	12	ns	
t_{PZL}				7.5	11	1	12	1	12		
t_{PHZ}	\overline{OE}	Y	$C_L = 50\text{ pF}$	8	11	1	12	1	12	ns	
t_{PLZ}				8	11	1	12	1	12		
$t_{sk(o)}$			$C_L = 50\text{ pF}$		1**				1	ns	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

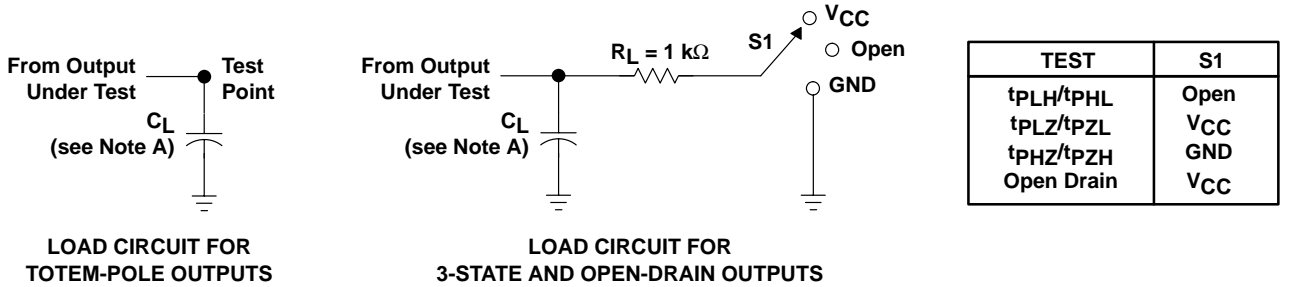
** On products compliant to MIL-PRF-38535, this parameter does not apply.

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load, $f = 1\text{ MHz}$	12	pF

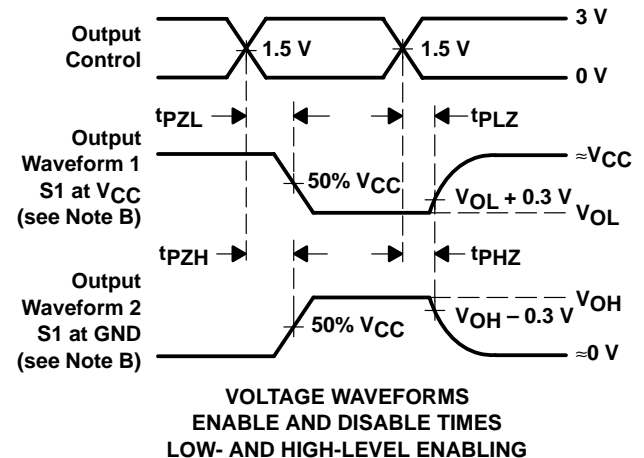
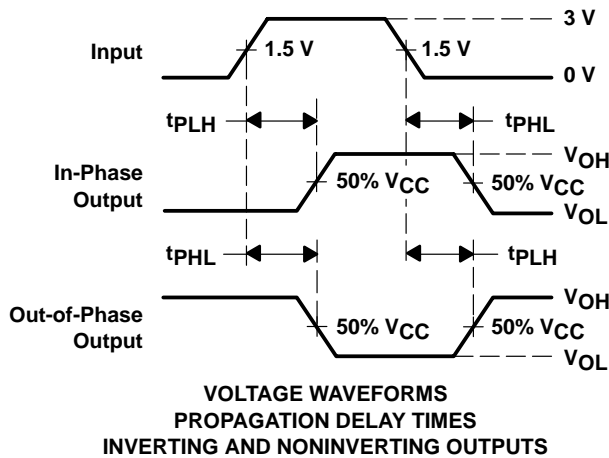
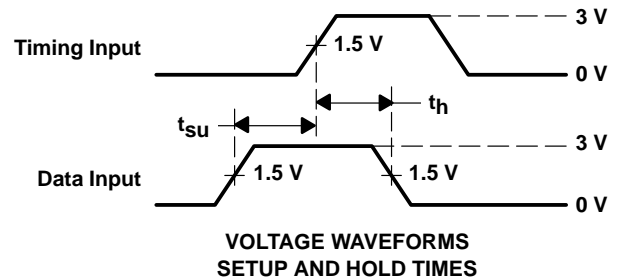
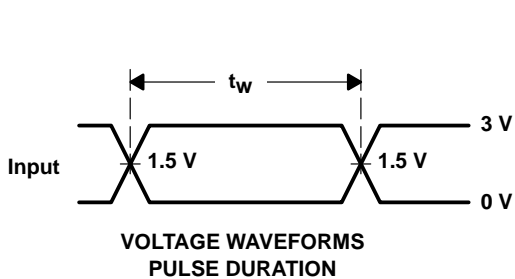


PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r \leq 3$ ns, $t_f \leq 3$ ns.
 D. The outputs are measured one at a time with one input transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9685101Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9685101QRA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9685101QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type
SN74AHCT540DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74AHCT540DBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DGVR	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DGVRE4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DGVRG4	ACTIVE	TVSOP	DGV	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT540NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AHCT540NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540PW	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540PWE4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540PWG4	ACTIVE	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540PWLE	OBSOLETE	TSSOP	PW	20		TBD	Call TI	Call TI
SN74AHCT540PWR	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT540PWRE4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AHCT540PWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AHCT540FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AHCT540J	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AHCT540W	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

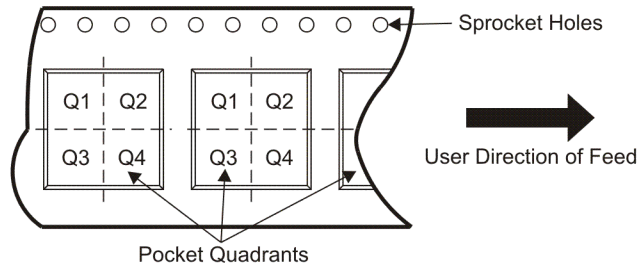
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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT540DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHCT540DGVR	TVSOP	DGV	20	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74AHCT540DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74AHCT540NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AHCT540PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT540DBR	SSOP	DB	20	2000	346.0	346.0	33.0
SN74AHCT540DGVR	TVSOP	DGV	20	2000	346.0	346.0	29.0
SN74AHCT540DWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AHCT540NSR	SO	NS	20	2000	346.0	346.0	41.0
SN74AHCT540PWR	TSSOP	PW	20	2000	346.0	346.0	33.0

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



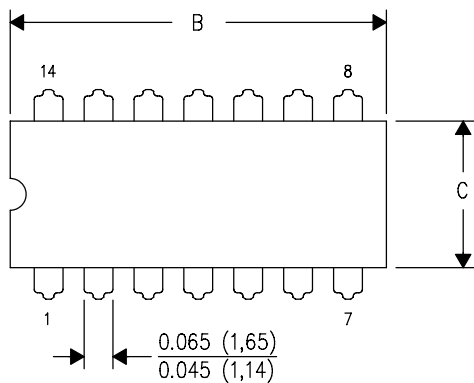
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- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

W (R-GDFP-F20)

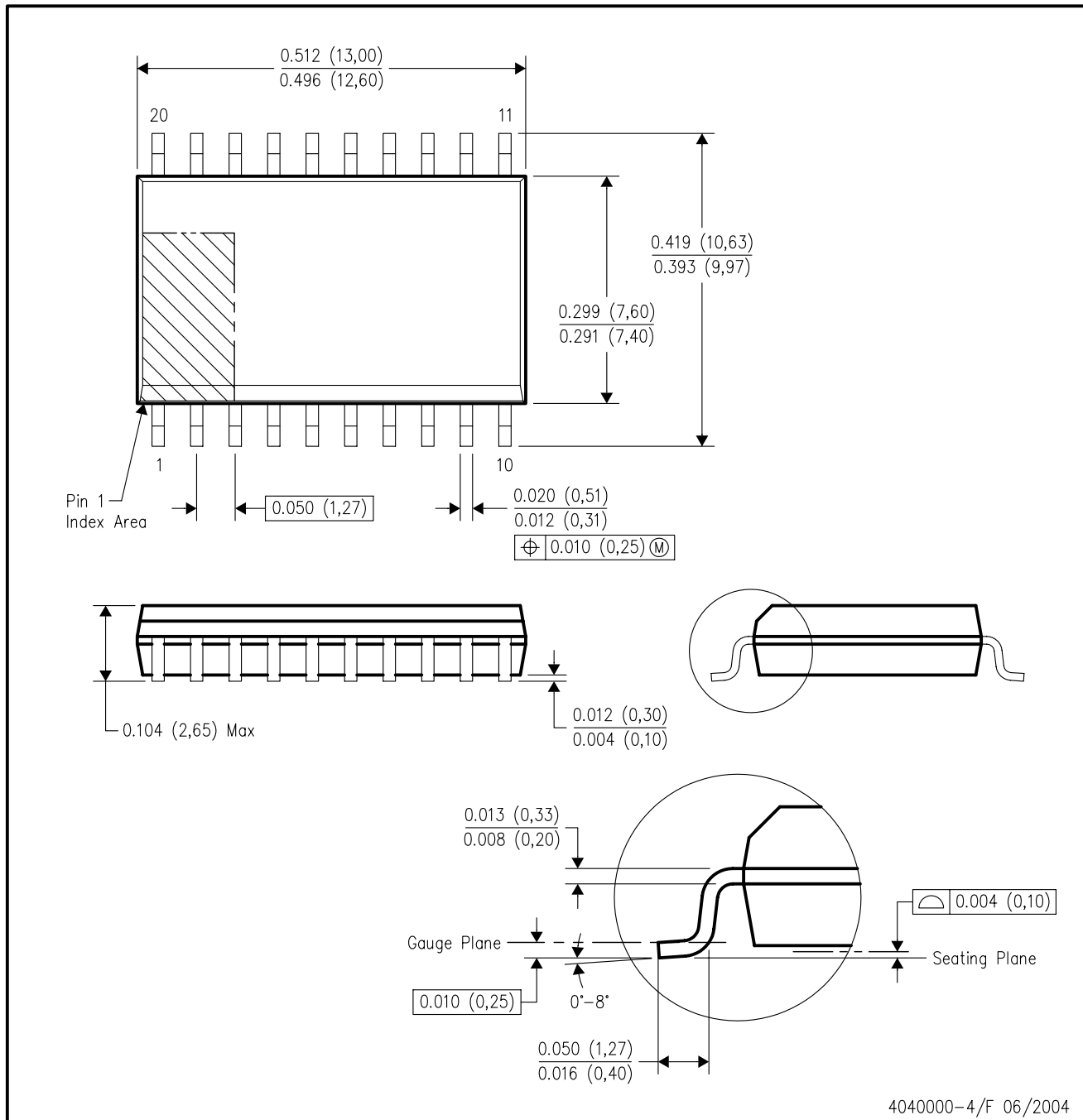
CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within Mil-Std 1835 GDFP2-F20

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

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